L Numbe:	r Hits	Search Text	DB	Time stamp
161	2594	257/704-707.ccls.	USPAT;	2003/04/06 14:30
			US-PGPUB;	* .
			EPO; JPO; DERWENT	*
162	640	438/125.ccls.	USPAT:	2003/04/06 14:30
			US-PGPUB;	2
		* . * .	EPO; JPO;	
163	1076	438/125	DERWENT USPAT;	2003/04/06 14:30
*	ļ		US-PGPUB;	2003/04/08 14:30
			EPO; JPO;	
164	1421	257/704	DERWENT USPAT;	2002/04/06 14:21
			US-PGPUB;	2003/04/06 14:31
		di V	EPO; JPO;	·
165	629	257/705	DERWENT	0000 (0000 0000 0000
			USPAT; US-PGPUB;	2003/04/06 14:31
			EPO; JPO;	
166	1878	257/706	DERWENT	
	10,0	2377700	USPAT; US-PGPUB;	2003/04/06 14:31
			EPO; JPO;	
167	1500	057 /707	DERWENT	
10/	1509	257/707	USPAT;	2003/04/06 14:32
			US-PGPUB; EPO; JPO;	
1.60	0.		DERWENT	
168	4086	257/704 257/705 257/706 257/707	USPAT;	2003/04/06 14:32
		*	US-PGPUB; EPO; JPO;	* ]
			DERWENT	e
169	5006	438/125 (257/704 257/705 257/706 257/707)	USPAT;	2003/04/06 14:33
	1		US-PGPUB;	
		*	EPO; JPO; DERWENT	
170	201469	(thermal conductive) near1 (material	USPAT;	2003/04/06 14:44
		adhesive)	US-PGPUB;	
		1	EPO; JPO; DERWENT	
171	883	((thermal conductive) near1 (material	USPAT;	2003/04/06 14:56
		adhesive)) with void	US-PGPUB;	
		*	EPO; JPO;	
172	18	(438/125 (257/704 257/705 257/706	DERWENT USPAT;	2003/04/06 14:36
		257/707)) and (((thermal conductive) near1	US-PGPUB;	2.003/04/00 14.30
		(material adhesive)) with void)	EPO; JPO;	
173	8849	thermally near1 (material adhesive)	DERWENT USPAT;	2003/04/06 14:55
		. ===== :::::::::::::::::::::::::::::::	US-PGPUB;	2003/04/00 14:35
			EPO; JPO;	
174	207880	((thermal conductive) near1 (material	DERWENT	2003/04/06 14:55
		adhesive)) (thermally near1 (material	USPAT; US-PGPUB;	2003/04/06 14:55
l		adhesive))	EPO; JPO;	
175	21372	(((thermal conductive) near1 (material	DERWENT	2002/04/06 14 55
		adhesive)) (thermally near1 (material	USPAT; US-PGPUB;	2003/04/06 14:58
		adhesive))) with (void hole opening	EPO; JPO;	
176	6056	recess)	DERWENT	
	0038	((((thermal conductive) near1 (material adhesive)) (thermally near1 (material	USPAT; US-PGPUB;	2003/04/06 14:59
		adhesive))) with (void hole opening	EPO; JPO;	
177	1046	recess)) and (chip die)	DERWENT	
1//	1946	(((((thermal conductive) near1 (material adhesive)) (thermally near1 (material	USPAT;	2003/04/06 15:00
		adhesive))) with (void hole opening	US-PGPUB; EPO; JPO;	
		recess)) and (chip die)) and (flipchip	DERWENT	
		(flip adj chip) bump ball)		

178	550			
1.0	553	(((((thermal conductive) near1 (material	USPAT;	2003/04/06 15:01
		adhesive)) (thermally near1 (material	US-PGPUB;	
		adhesive))) with (void hole opening	EPO; JPO;	
	-	recess)) and (chip die)) and (flipchip	DERWENT	1
		(flip adj chip) bump ball)) and (cap lid		
170		heatsink (heat adj sink))		
179	506	, ((((())))	USPAT;	2003/04/06 15:03
		adhesive)) (thermally near1 (material	US-PGPUB;	1
		adhesive))) with (void hole opening	EPO; JPO;	
		recess)) and (chip die)) and (flipchip	DERWENT	*
		(flip adj chip) bump ball)) and (cap lid		
		heatsink (heat adj sink))) and (substrate		
		(printed adj circuit adj board))		<u> </u>
180	373	''''   ''''   '''''   ''''''''   ''''''	USPAT;	2003/04/06 15:04
0.0		(material adhesive)) (thermally near1	US-PGPUB;	
		(material adhesive))) with (void hole	EPO; JPO;	
		opening recess)) and (chip die)) and	DERWENT	
		(flipchip (flip adj chip) bump ball)) and		
		(cap lid heatsink (heat adj sink))) and		
		(substrate (printed adj circuit adj		
		board))) and heat and solder		
181	315	((((((((thermal conductive) near1	USPAT;	2003/04/06 15:04
		(material adhesive)) (thermally near1	US-PGPUB:	2003/04/00 13:04
		(material adhesive))) with (void hole	EPO; JPO;	
i		opening recess)) and (chip die)) and	DERWENT	
į		(flipchip (flip adj chip) bump ball)) and	DERWENT	
		(cap lid heatsink (heat adj sink))) and		
		(substrate (printed adj circuit adj		
		board))) and heat and solder) and		
		semiconductor	×	